

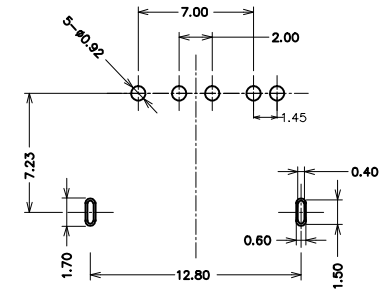
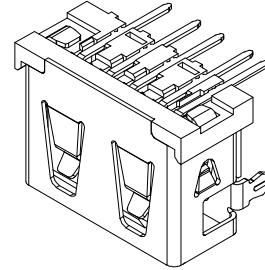
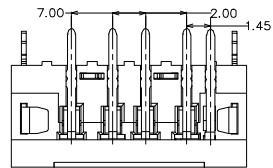
RoHS

MAPX

MODIFICATION

DRW

DATE



RECOMMEND P. C. B LAYOUT
TOLERANCE: ± 0.10

NOTES:

1. MATERIAL SPECIFICATION:

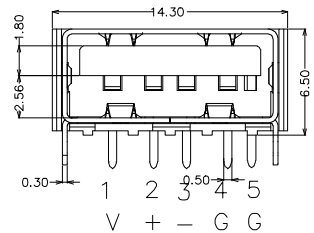
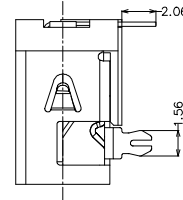
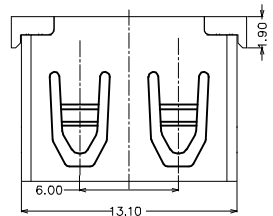
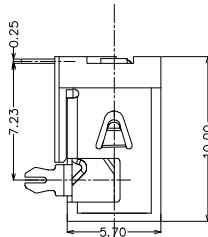
- 1) INSULATION MATERIAL: THERMOPLASTIC HALGENFREE.
- 2) SHELL: COPPER ALLOY T: 0.30mm
PLATING: NICKEL
- 3) TERMINAL: COPPER ALLOY T: 0.25mm
PLATING: GOLD/TIN PLATED;

2. ELECTRICAL CHARACTERISTIC:

- 1) INSULATION RESISTANCE: 1000M Ω MIN;
- 2) CONTACT RESISTANCE: 30m Ω MAX;
- 3) WITHSTANDING VOLTAGE: 500V AC;

3. MECHANICAL CHARACTERISTICS:

- 1) INSERTION FORCE: 3.57Kgf Max;
- 2) EXTRACTION FORCE: 1.02Kgf Min;



产品图				易芯精密科技(浙江)有限公司			
PRODUCT CHART DWG				Easychips Precision Technology (Zhejiang) Co., Ltd.			
公差一览表				单位	MM	制图	ZYB
TOLERANCE UNLESS OTHERWISE				UNITS		DRAWING	
X.	± 0.35	X.	$\pm 5.^\circ$	比例	1:1	审核	制图料号
.X	± 0.20	.X	$\pm 2.^\circ$	SCALE		CHKD	PRODUCT PART NO.
.XX	± 0.15	.XX	$\pm 1.^\circ$	日期	2016-09-08	核准	产品名称
.XXX	± 0.05	.XXX	$\pm 0.5^\circ$	DATE		APPD	PRODUCT NO.
				角法	角法	版本	A0
				VIEW		VER	